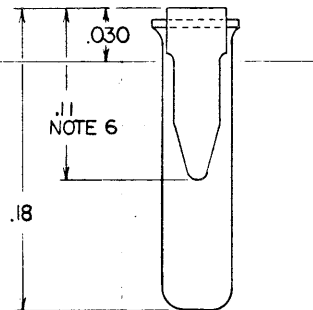
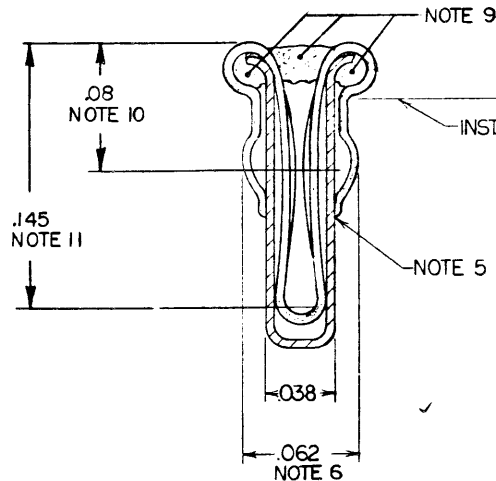
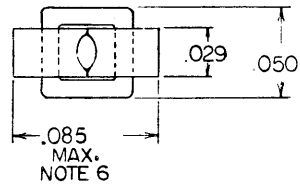


PRODUCT NO.	NOTE
75315-001	As Shown

REVISIONS			
REV	DESCRIPTION	BY	DATE
F	REDRAWN	DEW	7-9-77
G	ADDED NOTE 10	DCH	11-1-77
H	ADD P/N -002	TE	4-30-78
J	DELETED-002, ADDED DIM'S .08 +.145, REVISED NOTES 1,3,4,6,8, & 10. ADDED NOTE 11, DELETED DIMPLE ON DWG	DA	1-25-80
K	SPRING WIDTH .085 WAS .080	BM	9/15/84



NOTES:

1. THE SOCKET ASSY SHALL BE SELF RETAINING DURING WAVE SOLDERING IN HOLES FROM .050 TO .058 DIA.
2. THE SPRING SHALL SOLDER TO THE CUP DURING WAVE SOLDERING IN SINGLE OR DOUBLE SIDED BOARDS TO 1/16 THK. NO SOLDER SHALL ENTER THE INSIDE OF THE CUP.
3. THE SOCKET SHALL ACCEPT ROUND LEADS FROM .012 TO .022 DIA. AND FLAT LEADS WHEN PROPERLY ORIENTED FROM .008 TO .015 THK. BY .020 TO .025 WIDE.
4. SEE PRODUCT SPEC 12-006 FOR INSERTION / WITHDRAWAL FORCES.
5. GAP BETWEEN SPRING TIPS AND CUP NOT TO EXCEED .003.
6. DIMENSIONS APPLY PRIOR TO INSTALLATION
7. CUP MATERIAL: GILDING MATERIAL PER MIL.-C-21768. SPRING MATERIAL: B+C<sub>u</sub> PER QQ-C-533.
8. CUP PLATING: TIN-LEAD 60/40 1,50μ / 60μ THK. SPRING PLATING: 0,76μ / 30μ GOLD (MIL G45204B) TYPE IC, OVER 1,01μ / 40μ NICKEL (QQ-N-290)
9. R.T.V. APPLIED TO AREA SHOWN TO PREVENT FLUX AND SOLDER FROM ENTERING SOCKET DURING WAVE SOLDERING.
10. SHOWS CENTER LINE OF THEORETICAL POINT OF CONTACT FROM TOP OF SPRING
11. SHOWS MAX. DEPTH FOR .020 LEAD FROM TOP OF SPRING

CUSTOMER COPY FOR REFERENCE ONLY

DO NOT SCALE DRAWING		TOLERANCES UNLESS OTHERWISE NOTED		INCH	MM	DATE	9-9-77
NEXT ASSY		THIRD ANGLE PROJECTION		LINEAR	.000 ± .008	NOTE 7	
USED ON	APPLICATION	INCH	RADII	ANGLES	ENGR	NOTE 8	
		MM	ANGLES		FINISH		
					SCALE	SIZE	DWG. NO.
					3-24-77	X	C 75315
					SHEET 1 OF 1		

**BERG ELECTRONICS**  
E. I. DU PONT DE NEMOURS & COMPANY  
NEW CUMBERLAND, PA.

TITLE: **MINISRET SOCKET**

SCALE: X SIZE: C DWG. NO.: 75315 SHEET 1 OF 1